## PRELIMINARY DATA SHEET



## **GaAs HBT INTEGRATED CIRCUIT**

# **uPG2314T5N**

## POWER AMPLIFIER FOR Bluetooth™ Class1

#### DESCRIPTION

The uPG2314T5N is a GaAs HBT MMIC power amplifier which was developed for Bluetooth™ Class1.

This device realizes high efficiency, high gain and high output power by using InGaP HBT.

This device is housed in a 6-pin TSON(Thin Small Out-line Non-Leaded) package. And this package is able to high-density surface mounting.

#### **FEATURES**

 Operating Frequency : fopt = 2400 to 2500MHz (2450MHz TYP.)

 Supply Voltage :  $V_{CC1,2} = 2.7 \text{ to } 3.6 \text{V} (3.0 \text{V TYP.})$  Control Voltage :  $V_{cont} = 0$  to 3.6V (3.0V TYP.)

: V<sub>bias</sub> + V<sub>enable</sub> = 0 to 3.1V (3.0V TYP.) Circuit Current : Icc = 65mA TYP. @ Vcc1,2 = 3.0V, Vbias + Venable = 3.0V, Vcont = 3.0V, Pin = 0dBm Output Power : Pout = +20.0dBm TYP.@ Vcc1,2 = 3.0V, Vbias + Venable = 3.0V, Vcont = 3.0V, Pin = 0dBm

: GCR = 23dB TYP.@  $Vcc_{1,2}$  = 3.0V,  $V_{bias}$  +  $V_{enable}$  = 3.0V,  $V_{cont}$  = 0 to 3.0V,  $P_{in}$  = 0dBm High Efficiency : PAE = 50% TYP.

: 6-pin TSON package  $(1.5 \times 1.5 \times 0.37 \text{ mm})$ High-density surface mounting

#### **APPLICATION**

Gain Control Range

Power Amplifier for Bluetooth<sup>™</sup> Class1

#### ORDERING INFORMATION

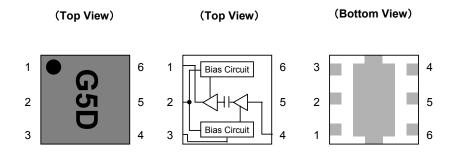
Part Number	Order Number	Package	Marking	Supplying Form
uPG2314T5N – E2	uPG2314T5N – E2 – A	6-pin plastic TSON (Pb-Free)	G5D	<ul><li>Embossed tape 8 mm wide</li><li>Pin1,6 face the perforation side of tape</li><li>Qty 3kpcs/reel</li></ul>

**Remark** To order evaluation samples, contact your nearby sales office. Part number for sample order: uPG2314T5N

#### Caution Electro-static sensitive devices

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

### PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No	Pin Name
1	OUTPUT / Vcc2
2	V <sub>bias</sub> + V <sub>enable</sub>
3	Vcont
4	INPUT
5	Vcc1
6	GND

## ASOLUTE MAXIMUM RATINGS (Unless otherwise specified, TA = +25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	VCC1,2	5.5	V
	V <sub>bias</sub> + V <sub>enable</sub>	3.6	V
Control Voltage	Vcont	3.6	V
Circuit Current	Icc	400	mA
Control Current	Icont	0.5	mA
Input Power	Pin	+10	dBm
Power Dissipation	Po	700 <sup>Note</sup>	mW
Operating Ambient Temperature	TA	-40 <b>∽</b> + 85	°C
Storage Temperature	Tstg	-55 <b>∽</b> +150	°C

**Note.** Mounted on double copper-clad 50  $\times$  50  $\times$  1.6mm epoxy glass PWB, T<sub>A</sub> = +85°C

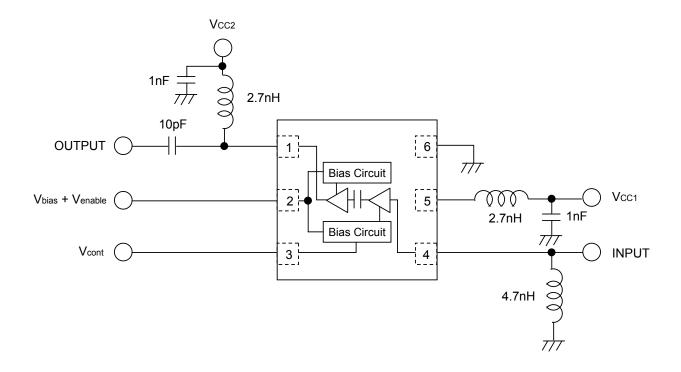
## RECOMMENDED OPERATING RANGE (Unless otherwise specified, TA = +25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	fopt	2400	2450	2500	MHz
Supply Voltage	VCC1,VCC2	2.7	3.0	3.6	V
	V <sub>bias</sub> + V <sub>enable</sub>	0	3.0	3.1	V
Control Voltage	Vcont	0	3.0	3.6	V

## ELECTRICAL CHARACTERISTICS ( $T_A = +25^{\circ}C$ , f = 2450MHz, $V_{CC1} = V_{CC2} = V_{bias} + V_{enable} = 3.0V$ , $P_{out} = +20dBm$ , External input and output matching, Unless otherwise specified)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	lcc	V <sub>cont</sub> = 3.0V, P <sub>in</sub> = 0dBm	-	65	70	mA
Shutdown Current	Ishut	V <sub>cont</sub> = 3.0V, P <sub>in</sub> = 0dBm, V <sub>bias</sub> +V <sub>enable</sub> = 0V	-	0	1	uA
Output Power1	Pout1	V <sub>cont</sub> = 3.0V, P <sub>in</sub> = 0dBm	+18.0	+20.0	-	dBm
Output Power2	Pout2	V <sub>cont</sub> = 0V, P <sub>in</sub> = 0dBm	-	-3.0	+1.0	dBm
Gain Control Range	GCR	V <sub>cont</sub> = 0 to 3.0V, P <sub>in</sub> = 0dBm	17	23	-	dB
Efficiency	PAE	V <sub>cont</sub> = 3.0V, P <sub>in</sub> = 0dBm	-	50	-	%

## **EVALUATION CIRCUIT**

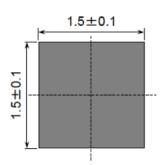


The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

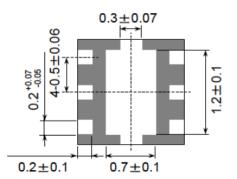
## **PACKAGE DIMENSIONS**

## 6-PIN PLASTIC TSON (UNIT: mm)

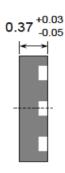
**Top View** 



#### **Bottom View**



### Side View



#### RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol	
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).



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Subject: Compliance with EU Directives

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CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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